


06-25-2003

Form PTO-1595 (Rev. 10/02) OMB No. 0651-0027 (exp. 6/30/2005) Tab settings ⇌ ⇌ ⇌	REC <div style="border: 1px solid black; padding: 2px; display: inline-block;">102481492</div>	U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.		
1. Name of conveying party(ies): Hiroto YASUURA Akihiko INOUE Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	2. Name and address of receiving party(ies) Semiconductor Technology Academic Name: <u>Research Center</u> Internal Address: _____ _____ 16-10, Shimbashi 6-chome Street Address: <u>Minato-ku, Tokyo 105-0004 Japan</u> _____ City: _____ State: _____ Zip: _____ Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
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4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: _____ A. Patent Application No.(s) _____ <u>09/454,561 (12/07/99)</u> B. Patent No.(s) _____ Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		
5. Name and address of party to whom correspondence concerning document should be mailed: Name: <u>WALLENSTEIN & WAGNER, LTD.</u> Attn: M. Morneau, Esq. Internal Address: _____ _____ Street Address: <u>311 South Wacker Drive</u> <u>Suite 5300</u> City: <u>Chicago</u> State: <u>IL</u> Zip: <u>60606</u>	6. Total number of applications and patents involved: <u>1</u> 7. Total fee (37 CFR 3.41).....\$ <u>40</u> <input checked="" type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to deposit account 8. Deposit account number: <u>23-0280</u>	
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9. Signature. <div style="display: flex; justify-content: space-between; align-items: flex-end;"> <div style="width: 30%;"> <u>Monique A. Morneau</u> Name of Person Signing </div> <div style="width: 30%; text-align: center;">  Signature </div> <div style="width: 30%; text-align: right;"> <u>June 19, 2003</u> Date </div> </div> <div style="text-align: right; margin-top: 5px;"> Total number of pages including cover sheet, attachments, and documents: <u>3</u> </div>		

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PATENT
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U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert
ASSIGNEE's
Name(s)
Address(es))

Semiconductor Technology Academic Research Center

16-10, Shimbashi 6-chome, Minato-ku, Tokyo 105-0004, Japan

(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of
Invention)

METHOD OF MANUFACTURING SYSTEM LSI

AND SYSTEM LSI MANUFACTURED USING THE METHOD

relating to International Patent Application PCT/JP _____/_____ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date
of execution
of application,
if not
concurrent)

- (a) executed on 11/30/99 ;
(b) filed on December 7, 1999 ,
Serial No. 09 / 454,561 ;

(Wallenstein & Wagner, Ltd.
Chicago, Illinois 60606-6622
) is hereby authorized to insert in (b) the specified
data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

1) <u>Hiroto Yasuura</u> (SIGNATURE)	Hiroto Yasuura (TYPE NAME)	30/11/1999 (DATE)
2) <u>Akihiko Inoue</u> (SIGNATURE)	Akihiko Inoue (TYPE NAME)	30/11/1999 (DATE)
3) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
4) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
5) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
6) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
7) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
8) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)